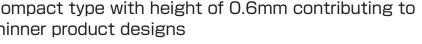
Compact type with height of 0.6mm contributing to thinner product designs







Typical Specifications

Items	Specifications
Rating (max.)	50mA 12V DC
Rating (min.)	10μA 1V DC
Initial contact resistance	500mΩ max.
Travel (mm)	0.13
Protective structure **	IP67 equivalent IP68 equivalent (SKSWDAE010)

■ Product Line

Product No.	Operating force	Operating direction	Operating life	Minimum ord	Drawing		
i ioddot ivo.	Operating force	Operating direction	(5mA 5V DC)	Japan	Export	No.	
SKSWCEE010	1.8N	Top push	300,000 cycles	- 20,000	20,000		
SKSWCFE010	2.4N		500,000 cycles			1	
SKSWCGE010	3.3N		300,000 cycles				
SKSWDAE010	2.4N		300,000 cycles			2	

■ Packing Specifications

Taping

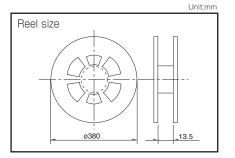
Numbe	Tape width	Export package			
1 reel	1 case / Japan	1 case / export packing	(mm)	measurements (mm)	
20,000	200,000	200,000	12	395×395×205	

Note

For reels of 330mm diameter, please inquire.

* Assumes the switch is left alone without being operated. Under the specified conditions, dust and water ingress with a significant impact on the switch's on-off function is prevented.

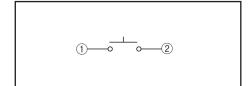
IP67 dust and water resistance is guaranteed for the switch alone and performance may not be guaranteed depending on the mounting conditions and usage.





■ Dim	■ Dimensions Unitmm						
No.	Style	PC board mounting hole and land dimensions (Viewed from switch mounting face)					
1	3.5						
	80	3.8					
2	3.5	50					

■ Circuit Diagram



	Type				Sh	arp Feeling T	ype			
Турс			<u> </u>	T	5	Surface Moun	it		T	1
	Series	SKSD	SKRN	SKTA	SKSV	SKSW	SKSF	SKSM	SKTK	SKSG
	Photo			NEW	•		•	•	NEW	0
	Features	Double	action			Compact size Low-profile	9		Long life	High operation force Compact size
	Water-proof	_	_	•	•	•	_	•	•	_
	Dust-proof	_	_	•	•	•	_	•	•	_
	IP standard	_	_	67 equivalency	67 equivalency	67 equivalency 68 equivalent in some cases	_	67 equivalency	67 equivalency	_
Operatir	Top push	•	•	•	•	•	•	•	•	•
directio		_	_	_	_	_	_	_	_	_
	W	4.1		2.6	2.8	3	2.8	3.4	5.9	3
Dimensio (mm)	ons D	3.9	□6	1.6	1.9	2	2.4	2.9	4	2.7
(11111)	Н	0.6	0.9	0.53	0.55	0.6	0.65	0.7	0.78	1.4
Operation force coverage	2N to 3N	for respect	evant pages ive product ptions	\$	Ĵ	1		‡	\$	1
	Travel (mm)		ant pages for uct descriptions	0.11	0.12	0.13	(D.1	0.25	0.12
G	round terminal	•	•	_	_	_	_	_	_	0
Operatin	ng temperature range	-40℃ t	o +90°C			_	30℃ to +8!	5°C		
А	utomotive use	_	_	_	_	_	_	_	_	•
	Life Cycle	* 2	* 2	* 2	* 2	* 2	X 2	* 2	* 2	* 2
	Rating (max.) (Resistive load)				5	0mA 12V D	С			
Electrical	Rating (min.) (Resistive load)	10μA 1V DC								
performance	Insulation resistance		100MΩ min. 100V DC 1min. 50MΩ min. 100V DC 1min. 100V DC 1min. 100V DC 1min.							
	Voltage proof	100V AC 1min.	250V AC 1min.			1	00V AC 1m	in.		
Durahilitu	Vibration		10	to 55 to 104 in the 3	Hz/min., the a	amplitude is 1 K, Y and Z for	.5mm for all 2 hours res	the frequenc spectively	ies,	
Durability	Lifetime	Shall be in accordance with individual specifications.								
	Cold	-40°C 96h								
Environmental performance	Dry heat	90°C 96h								
	Damp heat	60°C, 90 to 95%RH 96h								
	Page	219	220	221	222	223	225	226	227	228

W: Width. The most outer dimension excluding terminal portion.

Notes

 $[\]mathsf{D}:\mathsf{Depth}.$ The most outer dimension excluding terminal portion. H: Height. The minimum dimension if there are variances.

^{1.} The automotive operating temperature range to be individually discussed upon request.

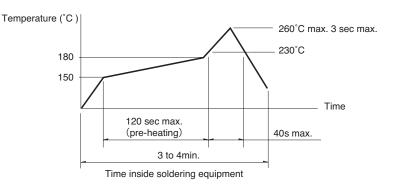
^{2. •} Indicates applicability to all products in the series, while \bigcirc indicates applicability to some products in the series.

TACT Switch™ Soldering Conditions

Condition for Reflow

Available for Surface Mount Type.

- 1. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at solder joints (copper foil surface).
 - A heat resistive tape should be used to fix thermocouple.
- 2. Temperature profile



Notes

- The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others.
 The above-stated conditions shall also apply to switch surface temperatures.
- Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Conditions for Auto-dip

Available for Snap-in Type and Radial Type.

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKHH, SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKQJ, SKQK, SKEG Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	45s max.
Soldering temperature	255℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

Manual Soldering

Items		Condition
	Soldering temperature	350℃ max.
	Duration of soldering	3s max.
	Capacity of soldering iron	60W max.

SKHH, SKHW, SKRG, SKPD Series

Items	Condition
Soldering temperature	360°C max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKTD, SKTG, SKQJ, SKQK, SKEG Series

Items	Condition
Soldering temperature	350°C max.
Duration of soldering	3s max.
Capacity of soldering iron	20W max.

Notes

- 1. Prevent flux penetration from the top side of the TACT Switch™.
- 2. Switch terminals and a PC board should not be coated with flux prior to soldering.
- 3. The second soldering should be done after the switch is stable with normal temperature.
- 4. Use the flux with a specific gravity of min 0.81. (EC-19S-8 by TAMURA Corporation, or equivalents.)

